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**(54) OZONE WATER
CLEANING SYSTEM OF
SEMICONDUCTOR WAFER**

(57) Abstract:

PROBLEM TO BE SOLVED: To lessen a time required for removing resist from a semiconductor wafer by a method wherein a heater used for heating ozone water is provided onto an ozone water feed line between a cleaning tank and an ozone water generating device.

SOLUTION: An ozone water feed line 4 is connected to an ozone water generating device 6, and a heater 5 is provided to an ozone water feed line 4. A cleaning tank 2 is provided to the outlet of the ozone water feed line 4. In this constitution, ozone water generated by the ozone water generating device 6 is heated by the heater 5 and fed to the cleaning tank 2. Ozone water fed to the cleaning tank 2 is supersaturated as it is kept at high temperatures, and the ozone water gets quickly decomposed because it is kept under a normal pressure when it is introduced into the cleaning tank 2. When a semiconductor wafer 1 is introduced into the cleaning tank 2 that is kept in the condition as mentioned above, ozone reacts quickly on resist. Therefore, a time required for removing resist from a semiconductor wafer can be shortened.

